



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Salman Akram

**Serial No.:** 10/791,191

**Filed:** March 2, 2004

**For:** METHOD OF IMPROVING COPPER  
INTERCONNECTS OF  
SEMICONDUCTOR DEVICES FOR  
BONDING

**Confirmation No.:** 1968

**Examiner:** L. Gurley

**Group Art Unit:** 2812

**Attorney Docket No.:** 2269-3854.3US  
(98-0854.03/US)

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

June 23, 2005  
Date

*Leta M. Howard*  
Signature

Leta M. Howard  
Name (Type/Print)

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**AMENDMENT**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This amendment is in response to the Office Action of March 23, 2005 whose initial period of response is set to expire on June 23, 2005.

**Amendments to the Specification** begin on page 3 of this paper.

**Amendments to the Drawings** begin on page 12 of this paper and include attached replacement and annotated drawing sheets.

**Serial No. 10/791,191**

**Amendments to the Claims** are reflected in the listing of claims which begins on page 13 of this paper.

**Remarks/Arguments** begin on page 16 of this paper.

An **Appendix** including replacement and annotated drawing sheets is attached following page \_\_ of this paper.